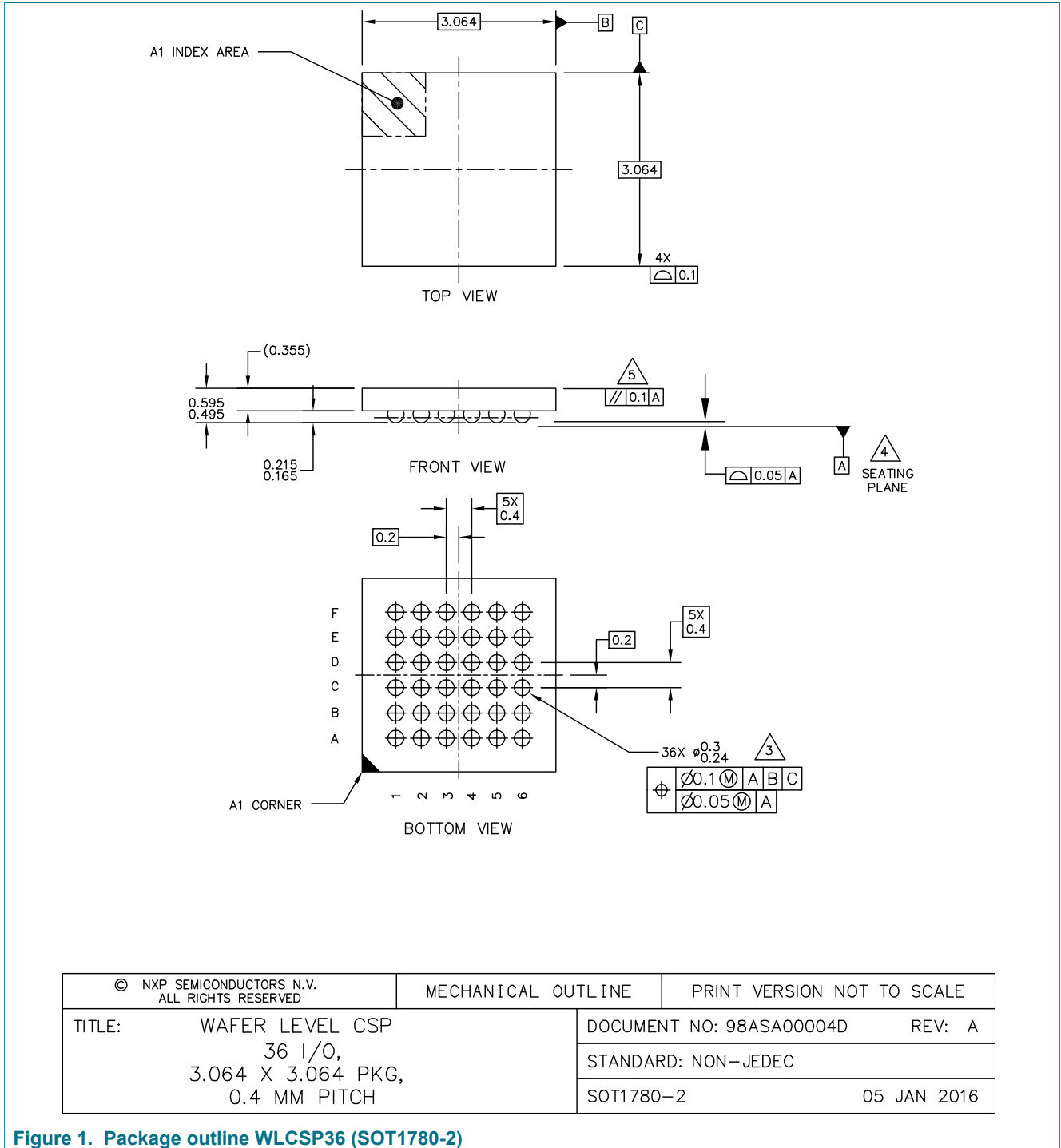# SOT1780-2

WLCSP36, wafer level chip-size package; 36 terminals; 0.4 mm pitch; 3.064 mm x 3.064 mm x 0.545 mm body

25 March 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	05-01-2016
Manufacturer package code	98ASA00004

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.964	3.064	3.164	mm
package width	2.964	3.064	3.164	mm
package height	0.495	0.545	0.595	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	

2 Package outline

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TITLE: WAFER LEVEL CSP 36 I/O, 3.064 X 3.064 PKG, 0.4 MM PITCH	DOCUMENT NO: 98ASA00004D		REV: A
	STANDARD: NON−JEDEC		
	SOT1780−2		05 JAN 2016

Figure 1. Package outline WLCSP36 (SOT1780-2)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: WAFER LEVEL CSP 36 I/O, 3.064 X 3.064 PKG, 0.4 MM PITCH	DOCUMENT NO: 98ASA00004D REV: A	
	STANDARD: NON−JEDEC	
	SOT1780−2	05 JAN 2016

Figure 2. Package outline note WLCSP36 (SOT1780-2)

3   Legal information

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